



## SOT-89 物料成分表

### Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition		CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English			
Die	5.6	Si	7440-21-3	100.00%	
Lead Frame	30.24	Cu	7440-50-8	balance	
		Fe	7439-89-6	0.05-0.15	
		P	7723-14-0	0.025-0.04	
		Ag	7440-22-4	0.05	
Epoxy	0.224	Silver Powder	7440-22-4	70-90%	
		Epoxy Resin A	9003-36-5	10-20%	
		Epoxy Resin B	Trade Secret	1-5%	
		Diluent	3101-60-8	5-10%	
		Phenolic Hardener	Trade Secret	1-5%	
		Dicyandiamide	461-58-5	0.1-1%	
wire	0.224	Copper	231-159-6	≥99.99	
		Silver	231-131-3	<20ppm	
		other	-	-	
Mold Compound	19.6	Epoxy Resin A	Trade Secret	1-5%	
		Epoxy Resin B	29690-82-2	1-5%	
		Phenol Resin	Trade Secret	1-5%	
		Silica(Amorphous)A	60676-86-0	70-90%	
		Silica(Amorphous)B	7631-86-9	1-5%	
		Carbon Black	1333-86-4	0.1-1%	
Plating	0.112	Sn	7440-31-5	99.99%	
Total	56				

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.